TO-553 Ŀ
Schottky Barrier Diode in a TO-220 Plastic Package.

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Low forward voltage drop,low poer losses,High efficiency operation.

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For use in high frequency inverters, switching

Parameter	N Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	100	V
RMS Reverse Voltage	V_{RMS}	70	V
Average Rectified Forward Current	$I_{F(AV)}$	2×20	A
Non Repetitive Peak Surge Current	I_{FSM}	300	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40˙ +150	

Parameter	N Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	I_R=1mA(Ta=25)	100			V
Forward Voltage	V_F	I_F =5A(Ta=25)		0.45		V
		I_F =10A(Ta=25)		0.54		V
		I_F =20A(Ta=25)		0.67	0.75	V
		I_F =5A(Ta=125)		0.38		V
		I_F =10A(Ta=125)		0.49		V
		I_F =20A(Ta=125)		0.62	0.65	V
Instantaneous Reverse Current	I_R ˆ Note 1˜	V_R=100V(Ta=25)		30	200	μA
		V_R=100V(Ta=125)				

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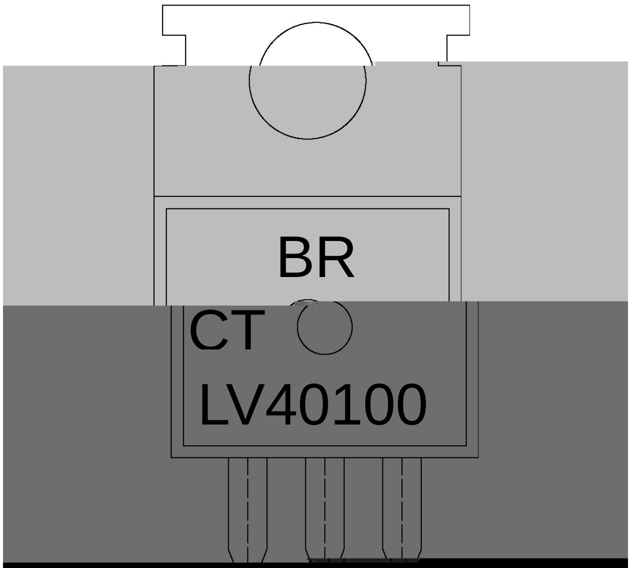

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Note:

BR:	Company Code
LV40100	Product Type.
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

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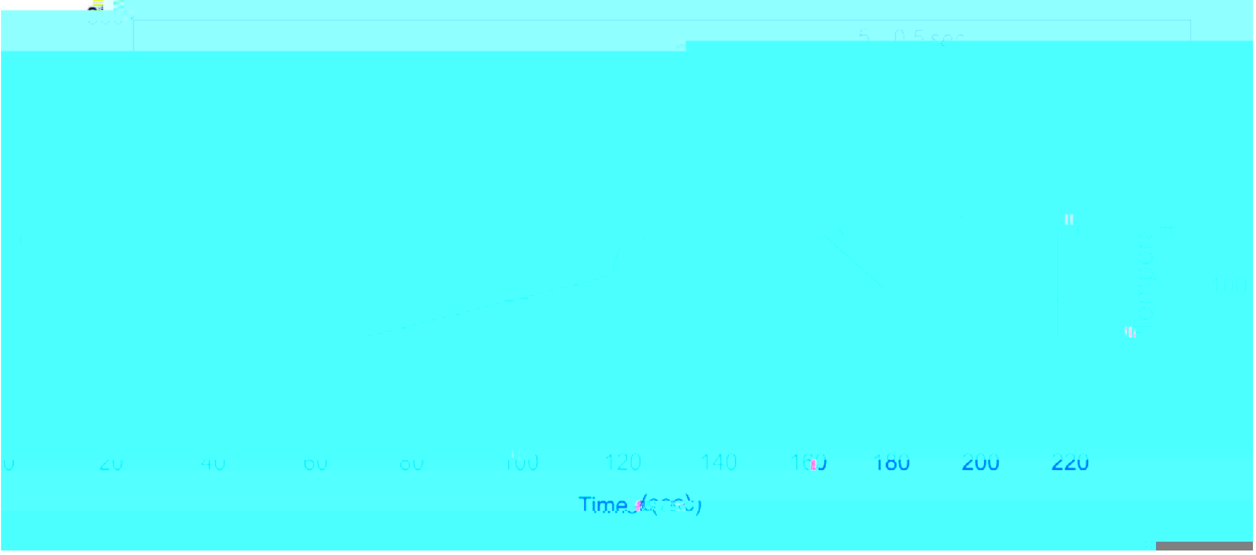

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1 ĺ 25 150 ڗ 60 90sec;

2 255±5 ڗ ﾊ 5±0.5sec;

3 ܗ 2 10 /sec.

Note:

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

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270±5 ڗ 10±1 sec.

Temp.:270±5 Time:10±1 sec

១ Ŀ ⋜— / Packaging SPEC.

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Package Type	Units	Dimension (unit mm^3)